

L Number	Hits	Search Text	DB	Time stamp
1	34	Benzocyclobutene with (photoresist photoimageable prepreg)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
2	326641	Benzocyclobutene with solder mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
3	0	Benzocyclobutene with solder with mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
4	327599	polyimide with solder mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:22
5	133	polyimide with solder with mask	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:35
6	1250	(257/690).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:35
7	28	(Benzocyclobutene with (photoresist photoimageable prepreg)) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
8	18	("5477933"   "5627405"   "5767010"   "5786270"   "5817541"   "5844304"   "5858815"   "5862816"   "5863812"   "5872051"   "5877079"   "5879964"   "5886398"   "5889332"   "5891795"   "5892273"   "5892290"   "5987744").PN.	USPAT	2002/11/09 15:35
9	816	(257/691).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
10	976	(257/698).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
11	1195	(257/700).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:59
14	34	((257/700).CCLS.) and (metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepreg)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:01
12	10	(metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepreg) and ((257/691).CCLS.)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:01
13	38	((257/698).CCLS.) and (metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepreg)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:31
15	3	("6441487" "6361926").pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:32
16	2	("6441487" "6361926").pn.	USPAT	2002/11/09 16:32

-	2056	257/690	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:15
-	1250	257/690.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:16
-	230	257/690.ccls. and substrate with pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:18
-	0	insulating with substra with pad and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:19
-	1142	insulating with substrate with pad and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:19
-	116	(insulating with substrate with pad and 257/\$.ccls.) and foil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:21
-	26119	foil with adhesi\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:21
-	25980	foil with adhesi\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:21
-	1263	(foil with adhesi\$5) and insulating with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:22
-	158	((foil with adhesi\$5) and insulating with substrate) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:26
-	9	foil with dentritic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:33
-	117	(metal foil wiring pad pattern) with rough\$5 same adhes\$7 and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 10:35
-	90	(metal foil wiring pad pattern) with rough\$5 same adhes\$7 and 257/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:34
-	7	("4816426"   "5329423"   "5523586"   "5661088"   "5726500"   "5801447"   "5872393").PN.	USPAT	2002/11/09 11:00

-	17	("3380155"   "3823348"   "4021838"   "4122479"   "4250520"   "4675717"   "4774630"   "5086327"   "5187715"   "5212406"   "5228777"   "5289637"   "5311278"   "5326984"   "5463249"   "5506418"   "5543641").PN.	USPAT	2002/11/09 11:08
-	11	5086327.URPN.	USPAT	2002/11/09 11:08
-	12	5726500.URPN.	USPAT	2002/11/09 11:08
-	1881	(metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 16:00
-	0	((metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.) and springboard	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:39
-	564	((metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.) and copper	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 11:39
-	501	((metal foil wiring pad pattern) with (chip die semiconductor IC) same (solder with mask photoresist photoimageable prepeg) and 257/\$.ccls.) and copper ) and ( aluminum gold silver nickel chrome)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/11/09 15:01
-	19	("4462534"   "5024372"   "5220200"   "5261593"   "5293067"   "5346861"   "5381848"   "5388327"   "5455390"   "5504277"   "5539153"   "5541460"   "5547740"   "5564617"   "5604379"   "5608262"   "5701032"   "5736456"   "5814894").PN.	USPAT	2002/11/09 11:42